



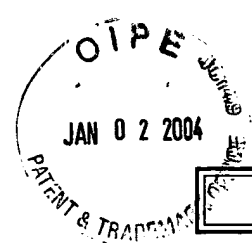
Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only

EFS ID: 53071
Application ID: 10669820
Title of Invention: REINFORCED DIE PAD SUPPORT
STRUCTURE
First Named Inventor: Chung Tzu
Domestic/Foreign Application: Domestic Application
Filing Date: 2003-09-24
Effective Receipt Date: 2004-01-02
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Statement
Filing Type:
Confirmation number: 5197
Attorney Docket Number: AMKOR090A




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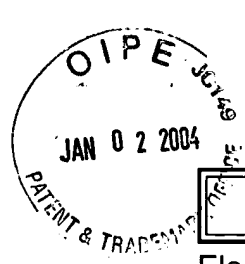
Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark
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**TRANSMITTAL**

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	REINFORCED DIE PAD SUPPORT STRUCTURE									
Application Number: 10/669820 										
Date: 2003-09-24										
First Named Applicant: Chung Hsing Tzu										
Confirmation Number: 5197										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids6-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids6-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids6-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

REINFORCED DIE PAD SUPPORT STRUCTURE

Application Number: 10/669820



Confirmation Number: 5197

First Named Applicant: Chung Tzu

Attorney Docket Number: AMKOR090A

Art Unit: 2811

Search string: (6395578 or 6400004 or 6410979 or 6414385
or 6420779 or 6429508 or 6437429 or 6444499
or 6448633 or 6452279 or 6464121 or 6476469
or 6476474 or 6482680 or 6498099 or 6498392
or 6507096 or 6507120 or 6534849 or 6559525
or 6566168).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6395578	2002-05-28	SHIN ET AL.			
	2	6400004	2002-06-04	FAN ET AL.			
	3	6410979	2002-06-25	ABE			
	4	6414385	2002-07-02	HUANG ET AL.			
	5	6420779	2002-07-16	SHARMA ET AL.			
	6	6429508	2002-08-06	GANG			
	7	6437429	2002-08-20	SU ET AL.			
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	17	6507096	2003-01-14	GANG
	18	6507120	2003-01-14	LO ET AL.
	19	6534849	2003-03-18	GANG
	20	6559525	2003-05-06	HUANG
	21	6566168	2003-05-20	GANG

Signature

Examiner Name	Date